Record Nr. UNINA9910820921703321 **Titolo** Electrodeposition [[electronic resource]]: properties, processes, and applications / / Udit Surya Mohanty, editor Pubbl/distr/stampa New York,: Nova Science Publishers, c2012 **ISBN** 1-61470-845-2 Edizione [1st ed.] 1 online resource (375 p.) Descrizione fisica Collana **Electrical Engineering Developments** Altri autori (Persone) MohantyUdit Surya 671.732 Disciplina Soggetti Alloy plating Electroplating Lingua di pubblicazione Inglese Materiale a stampa **Formato** Livello bibliografico Monografia Note generali Description based upon print version of record. Nota di bibliografia Includes bibliographical references at the end of each chapters and index. ""ELECTRODEPOSITION "": ""ELECTRODEPOSITION "": ""CONTENTS "": Nota di contenuto ""PREFACE ""; ""A REVIEW ON THE ELECTRODEPOSITION OF NICKEL: SYNTHESIS, MAGNETIC, THERMODYNAMIC PROPERTIES AND ITS POTENTIAL APPLICATIONS "": ""ABSTRACT "": ""INTRODUCTION "": ""1.1. CRYSTAL STRUCTURES OF NICKEL ""; ""1.2. SYNTHESIS ""; ""1.2.1. FCC Nickel ""; ""1.2.2. HCP Nickel""; ""1.3. MAGNETIC AND THERMODYNAMIC PROPERTIES ""; ""1.4. APPLICATIONS ""; ""CONCLUSION ""; ""REFERENCES""; ""DEPOSITION AND PROPERTIES OF ELECTROCHEMICAL COMPOSITE COATINGS ""; ""ABSTRACT ""; ""INTRODUCTION "" ""2.1. DIFFERENT TYPES OF ELECTROCHEMICAL COMPOSITE COATINGS (ECC) """"2.1.1. Nickel-Based ECC ""; ""2.1.2. Chromium-Based ECC ""; ""2.1.3. Copper-Based ECC ""; ""2.1.4. Iron-Based ECC""; ""2.1.5. Zinc-Based ECC ""; ""2.1.6. ECC Based on Noble Metals ""; ""CONCLUSION ""; ""REFERENCES ""; ""ELECTRODEPOSITION OF AU-SN ALLOYS ""; ""ABSTRACT""; ""INTRODUCTION ""; ""3.1. ELECTRODEPOSITION OF AU-SN ALLOYS FROM A SINGLE SOLUTION""; ""3.1.1. Solution Preparation ""; ""3.2. SOLUTION STABILITY ""; ""3.2.1. Solution Precipitation and Turbidity Measurements "" ""3.2.2. Characterization of Precipitates """"3.2.3. UV/Vis Spectroscopy

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